Final Product Change Notification | 201601011F01

Issue Date: 17-Apr-2016
Effective Date: 30-Jul-2016

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Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Process	[ ] Design
[ ] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Equipment	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Location	[ ] Electrical spec./Test coverage

Change of bond wire and new 2nd source mold compound in DFN2020-3 and DFN2020-6

Details of this Change

Scheduled changes affect transistors in DFN2020-3 (SOT1061) and DFN2020-6 (SOT1118) packages.

(1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.
(2) A second source mold compound supplier will be introduced.

Old product: Wire material is Au (with currently used mold compound suppliers)
Changed product: Wire material is Cu or Au (with currently used first and new second source mold compound supplier)

The design and materials of all other components will remain unchanged: die, die attach, and lead frame.

Reliability qualification and full electrical characterization over temperature has been performed. For details please see the Self Qualification Report.
No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
(2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM package. The second source supplier is already well established for NXP semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information
Samples are available upon request
Latest sample request date for PCN samples is 17-May-2016.
Production
Planned first shipment 30-Jul-2016

Impact

No impact to the products' functionality anticipated.
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 17-May-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com
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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC
BC52-16PA,115	934065819115
PBSS4260PAN,115	934066889115
PBSS4130PANP,115	934066882115
PBSS4112PANP,115	934066895115
PBSS4230PANP,115	934066885115
PBSS4160PAN,115	934066886115
BC68-25PA,115	934065737115
BC54PA,115	934065738115
BC69PA,115	934065748115
BC69-16PA,115	934065812115
BC51-16PA,115	934065816115
BC52PA,115	934065817115
BC53PA,115	934065821115
PBSS4112PAN,115	934066893115
BC56PA,115	934065745115
BC56-10PA,115	934065809115
BC69-25PA,115	934065813115
BC51PA,115	934065814115
BC53-16PA,115	934065823115
PBSS4260PANP,115	934066892115
BC68PA,115	934065736115
BC51-10PA,115	934065815115
PBSS5160PAP,115	934066887115
PBSS5112PAP,115	934066894115
BC54-16PA,115	934065806115
BC55-10PA,115	934065807115
PBSS4130PAN,115	934066879115
BC55PA,115	934065742115
BC52-10PA,115	934065818115
PBSS5230PAP,115	934066884115
BC54-10PA,115	934065805115
BC55-16PA,115	934065808115
BC56-16PA,115	934065811115
BC53-10PA,115	934065822115